

PRELIMINARY AMENDMENT  
U.S. Appln. No.: based on PCT/JP00/05044

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5. A solder resist composition to be used for manufacturing the multilayered printed circuit board according to claim 1,  
wherein an inorganic filler is mixed with a paste containing a resin for a solder resist layer.

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10. (amended) The multilayered printed circuit board according to claim 7,  
wherein said solder resist layer contains an inorganic filler.

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17. (amended) The multilayered printed circuit board according to claim 14,  
wherein said solder resist layer has a dielectric loss tangent of 0.01 or lower at 1 GHz.

18. (amended) The multilayered printed circuit board according to claim 14,  
wherein said solder resist layer is comprising a cycloolefin type resin.

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21. (amended) The multilayered printed circuit board according to claims 14,  
wherein said resin insulating layer is comprising a polyolefin type resin or a polyphenylene type resin.

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26. (amended) The multilayered printed circuit board according to claim 23,  
wherein said solder resist layer has a dielectric constant of 3.0 or lower at 1 GHz.

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27. (amended) The multilayered printed circuit board according to claim 24,  
wherein said polyphenylene ether resin is a thermosetting type polyphenylene ether  
resin and/or thermoplastic type polyphenylene ether resin.

28. (amended) The multilayered printed circuit board according to claim 23,  
wherein said resin insulating layer is comprising a polyphenylene ether resin.

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35. (amended) The multilayered printed circuit board according to claims 30,  
wherein said solder resist layer contains at least one member selected from the group  
consisting of a silicon compound, an aluminum compound and a magnesium compound.

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